

# Semiconductor Wafer Polishing and Grinding Equipment Market: Trends, Opportunities and Competitive Analysis [2023-2028]

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## Abstracts

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### Semiconductor Wafer Polishing and Grinding Equipment Market Trends and Forecast

The future of the global semiconductor wafer polishing and grinding equipment market looks promising with opportunities in the foundry, memory manufacturer, and IDMs industries. The global semiconductor wafer polishing and grinding equipment market is expected to reach an estimated \$0.33 billion with a CAGR of 5.0% from 2023 to 2028. The major drivers for this market are rise in the consumption of consumer electronics, increasing demand for MEMS, IC manufacturing, optics, and compound semiconductors, and growing trend for miniaturization of components.

### Semiconductor Wafer Polishing and Grinding Equipment Market by Type, and End Use Industry

A more than 150-page report is developed to help in your business decisions. Sample figures with some insights are shown below.

### Semiconductor Wafer Polishing and Grinding Equipment Market by Segments

### Semiconductor Wafer Polishing and Grinding Equipment Market by Segment

The study includes a forecast for the global semiconductor wafer polishing and grinding equipment market by type, end use industry, and region, as follows:

Semiconductor Wafer Polishing and Grinding Equipment Market by Type [Value (\$B) Shipment Analysis from 2017 to 2028]:

Semiconductor Wafer Polishing Equipment

Semiconductor Wafer Grinding Equipment

Semiconductor Wafer Polishing and Grinding Equipment Market by End Use Industry [Value (\$B) Shipment Analysis from 2017 to 2028]:

Foundries

Memory Manufacturers

IDMs

Others

Semiconductor Wafer Polishing and Grinding Equipment Market by Region [Value (\$B) Shipment Analysis from 2017 to 2028]:

North America

Europe

Asia Pacific

The Rest of the World

List of Semiconductor Wafer Polishing and Grinding Equipment Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies semiconductor wafer polishing and grinding equipment companies cater increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the semiconductor wafer polishing and grinding equipment companies profiled in this report include.

Applied Materials

Ebara Corporation

Disco Corporation

Lapmaster

Logitech

Entrepix

Revasum

Axis Technology

## Semiconductor Wafer Polishing and Grinding Equipment Market Insights

Lucintel forecast that semiconductor wafer polishing equipment will remain the largest type segment over the forecast period due to rapid expansion in the electronics industry that leads to increasing demand for micro electromechanical systems (MEMS), microchips, and integrated circuits for developing consumer electronic goods, such as smartphones, laptops and desktops..

Within this market, foundries is projected to record the highest growth from 2023 to 2028 due to their extensive utilization for composing integrated circuits, supported by the large-scale integration of wireless technologies, including the Internet of Things (IoT) and artificial intelligence (AI), that helps the manufacturers to develop smart devices.

North American region is expected to witness the highest growth during the forecast period due to increase in demand of power semiconductor ICs for automotive applications and growing investments in electric infrastructure in this region.

## Features of the Semiconductor Wafer Polishing and Grinding Equipment Market

Market Size Estimates: Semiconductor wafer polishing and grinding equipment market size estimation in terms of value (\$B)

**Trend and Forecast Analysis:** Market trends (2017-2022) and forecast (2023-2028) by various segments and regions.

**Segmentation Analysis:** Semiconductor wafer polishing and grinding equipment market size by various segments, such as by type, end use industry, and region

**Regional Analysis:** Semiconductor wafer polishing and grinding equipment market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

**Growth Opportunities:** Analysis on growth opportunities in different by type, end use industry, and regions for the semiconductor wafer polishing and grinding equipment market.

**Strategic Analysis:** This includes M&A, new product development, and competitive landscape for the semiconductor wafer polishing and grinding equipment market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

## FAQ

**Q1. What is the semiconductor wafer polishing and grinding equipment market size?**

**Answer:** The global semiconductor wafer polishing and grinding equipment market is expected to reach an estimated \$0.3 billion by 2028.

**Q2. What is the growth forecast for semiconductor wafer polishing and grinding equipment market?**

**Answer:** The global semiconductor wafer polishing and grinding equipment market is expected to grow with a CAGR of 5.0% from 2023 to 2028.

**Q3. What are the major drivers influencing the growth of the semiconductor wafer polishing and grinding equipment market?**

**Answer:** The major drivers for this market are rise in the consumption of consumer electronics, increasing demand for MEMS, IC manufacturing, optics, and compound semiconductors, and growing trend for miniaturization of components.

Q4. What are the major segments for semiconductor wafer polishing and grinding equipment market?

Answer: The future of the global semiconductor wafer polishing and grinding equipment market looks promising with opportunities in the foundry, memory manufacturers, and IDMs industries.

Q5. Who are the key semiconductor wafer polishing and grinding equipment companies?

Answer: Some of the key semiconductor wafer polishing and grinding equipment companies are as follows:

Applied Materials

Ebara Corporation

Disco Corporation

Lapmaster

Logitech

Entrepix

Revasum

Axis Technology

Q6. Which semiconductor wafer polishing and grinding equipment segment will be the largest in future?

Answer: Lucintel forecast that semiconductor wafer polishing equipment will remain the largest type segment over the forecast period due to rapid expansion in the electronics industry that leads to increasing demand for micro electromechanical systems (MEMS), microchips, and integrated circuits for developing consumer electronic goods, such as smartphones, laptops and desktops.

Q7. In semiconductor wafer polishing and grinding equipment market, which region is

expected to be the largest in next 5 years?

Answer: North American region is expected to witness the highest growth during the forecast period due to increase in demand of power semiconductor ICs for automotive applications and growing investments in electric infrastructure in this region.

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Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1. What are some of the most promising, high-growth opportunities for the semiconductor wafer polishing and grinding equipment market by type (semiconductor wafer polishing equipment and semiconductor wafer grinding equipment), end use industry (foundries, memory manufacturers, IDMs, and others), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q.2. Which segments will grow at a faster pace and why?

Q.3. Which region will grow at a faster pace and why?

Q.4. What are the key factors affecting market dynamics? What are the key challenges and business risks in this market?

Q.5. What are the business risks and competitive threats in this market?

Q.6. What are the emerging trends in this market and the reasons behind them?

Q.7. What are some of the changing demands of customers in the market?

Q.8. What are the new developments in the market? Which companies are leading these developments?

Q.9. Who are the major players in this market? What strategic initiatives are key players pursuing for business growth?

Q.10. What are some of the competing products in this market and how big of a threat do they pose for loss of market share by material or product substitution?

Q.11. What M&A activity did occur in the last five years and how did they impact the industry?

For any questions related to semiconductor wafer polishing and grinding equipment market or related to semiconductor wafer polishing and grinding equipment companies, semiconductor wafer polishing and grinding equipment market size, semiconductor wafer polishing and grinding equipment market share, semiconductor wafer polishing and grinding equipment analysis, write Lucintel analyst at email: [helpdesk@lucintel.com](mailto:helpdesk@lucintel.com) we will be glad to get back to you soon.

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